



# BUK7J2R4-80M

N-channel 80 V, 2.4 mOhm, Standard level MOSFET in LFPAK56E

4 April 2024

Preliminary data sheet

## 1. General description

Automotive qualified N-channel MOSFET using the latest Trench 14 low ohmic split-gate technology, for ultra-low  $R_{DSon}$  capability, housed in a LFPAK56E package. This product has been fully designed and qualified to meet AEC-Q101 requirements delivering high performance and endurance.

## 2. Features and benefits

- Fully automotive qualified to AEC-Q101:
  - 175 °C rating suitable for thermally demanding environments
- Trench 14 split-gate technology:
  - Reduced cell pitch enables enhanced power density and efficiency with lower  $R_{DSon}$  in same footprint
  - Fast and efficient switching with optimal damping and low spiking
- LFPAK Gull Wing leads:
  - High Board Level Reliability absorbing mechanical stress during thermal cycling, unlike traditional QFN packages
  - Visual (AOI) soldering inspection, no need for expensive x-ray equipment
  - Easy solder wetting for good mechanical solder joints
- LFPAK copper clip technology:
  - Improved reliability, with reduced  $R_{th}$ ,  $R_{DSon}$  and package inductance
  - Increases maximum current capability and improved current spreading

## 3. Applications

- 12 V, 24 V and 48 V automotive systems
- Motor, lighting and solenoid control
- Ultra high-performance power switching

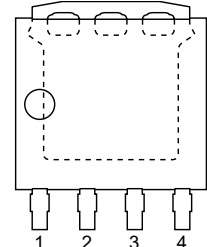
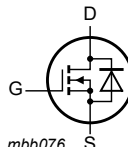
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	80	V
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 2</a>	-	-	231	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 1</a>	-	-	294	W
$T_j$	junction temperature		-55	-	175	°C
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$ ; $I_D = 25\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 11</a>	1.3	1.9	2.4	mΩ
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 25\text{ A}$ ; $V_{DS} = 40\text{ V}$ ; $V_{GS} = 10\text{ V}$ ; <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>	42.5	85	127	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>LPAK56E; Power-SO8 (SOT1023)</p>	 <p>mbb076</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK7J2R4-80M	LPAK56E; Power-SO8	plastic, single-ended surface-mounted package (LPAK56E); 4 leads; 1.27 mm pitch	SOT1023

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK7J2R4-80M	72M480J

## 8. Limiting values

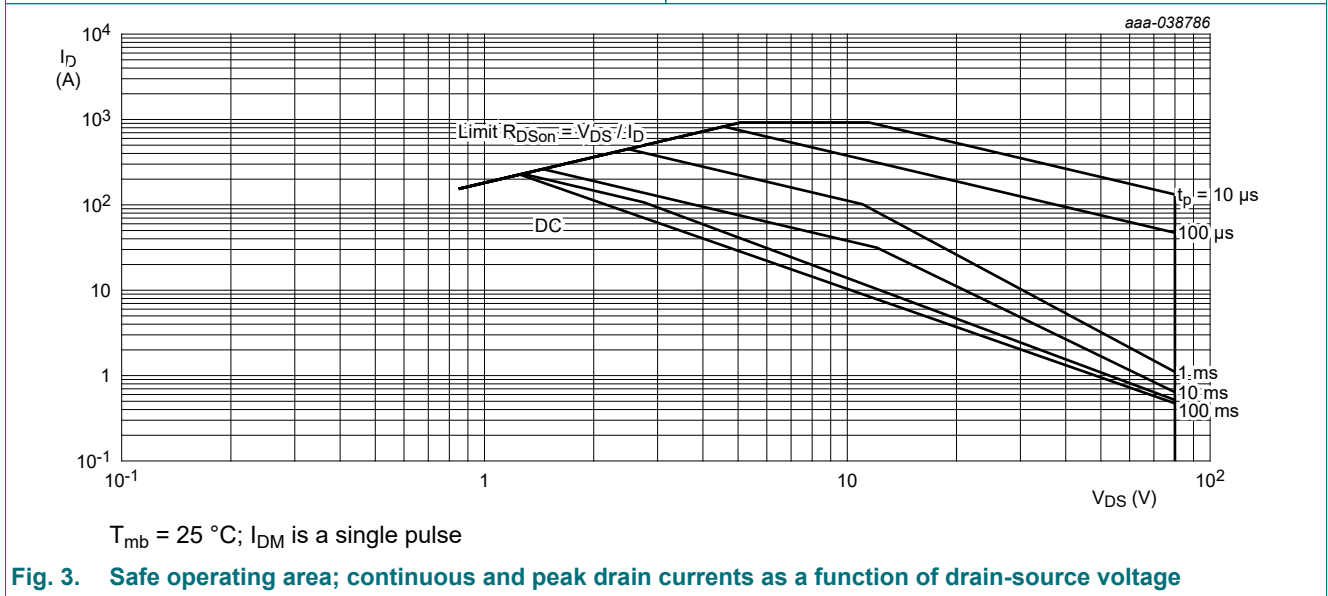
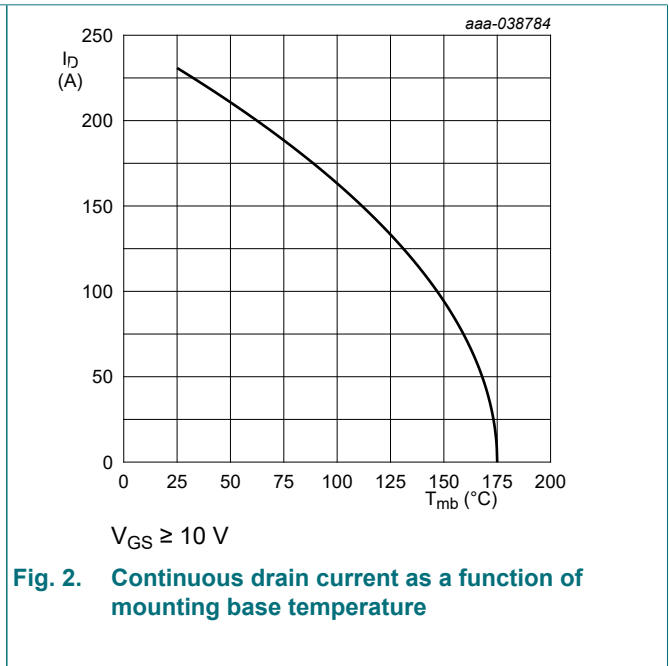
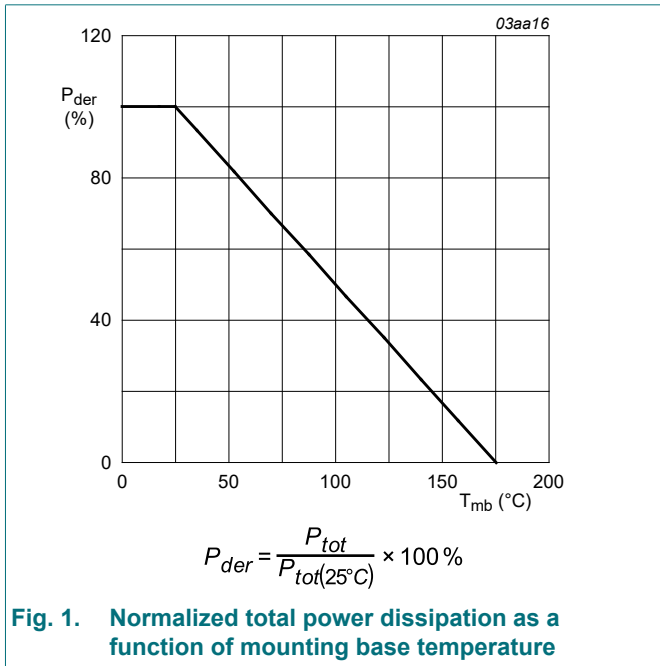
Table 5. Limiting values

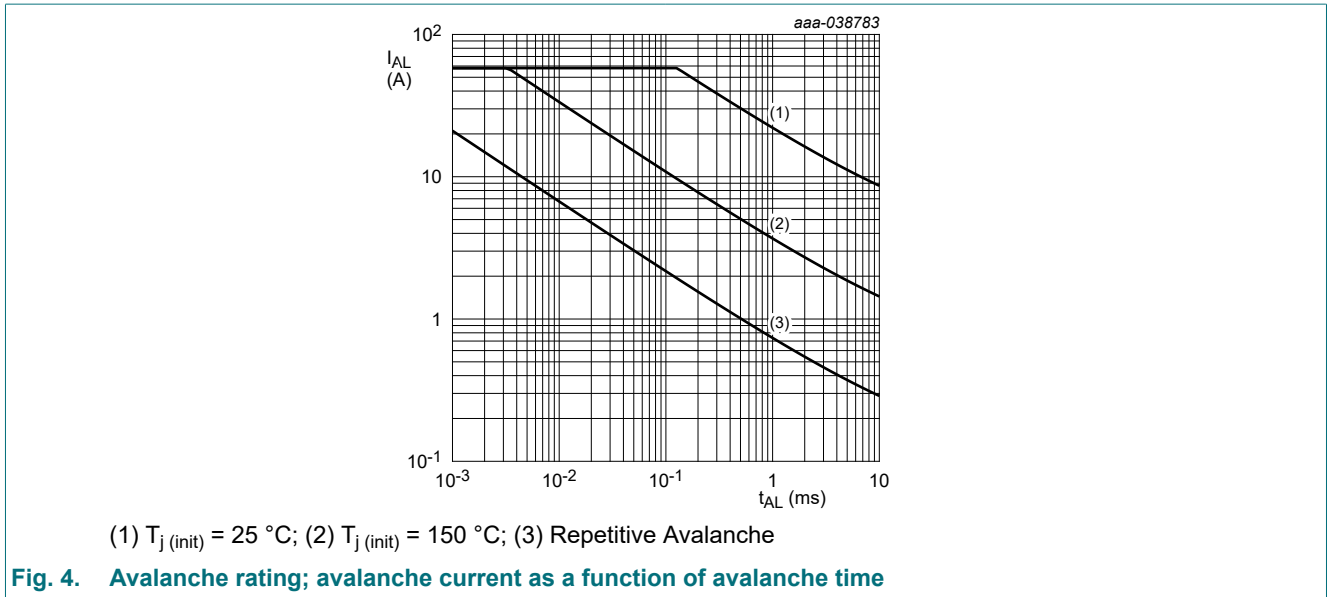
In accordance with the Absolute Maximum Rating System (IEC 60134).  $T_j = 25\text{ °C}$  unless otherwise stated.

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	80	V
$V_{GS}$	gate-source voltage		-20	20	V
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; Fig. 1	-	294	W
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; Fig. 2	-	231	A
		$V_{GS} = 10\text{ V}$ ; $T_{mb} = 100\text{ °C}$ ; Fig. 2	-	163	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$ ; Fig. 3	-	923	A
$T_{stg}$	storage temperature		-55	175	°C
$T_j$	junction temperature		-55	175	°C
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$	-	231	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$	-	923	A

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 58 \text{ A}$ ; $V_{sup} \leq 80 \text{ V}$ ; $R_{GS} = 50 \text{ }\Omega$ ; $V_{GS} = 10 \text{ V}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; unclamped; <a href="#">Fig. 4</a>	[1] [2] [3]	-	383 mJ

- [1] Protected by 100% test.
- [2] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [3] Refer to application note AN10273 for further information.





### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	0.45	0.51	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	[1]	-	24	-	K/W

[1] Device on 4 layer PCB. Refer to TN00008 for further information.

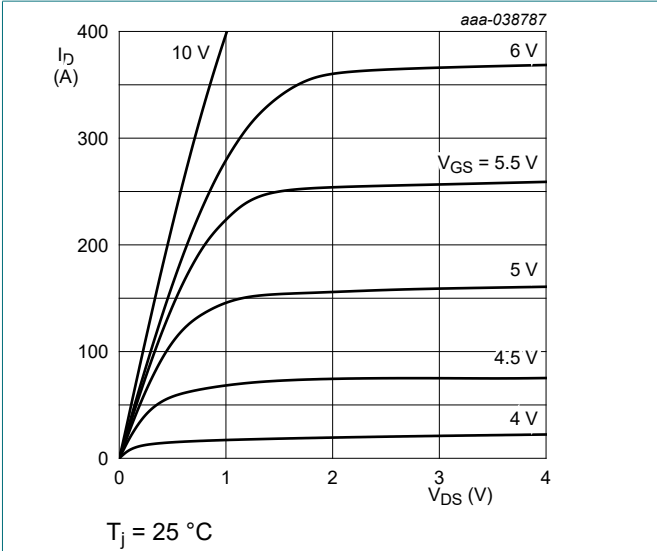


## 10. Characteristics

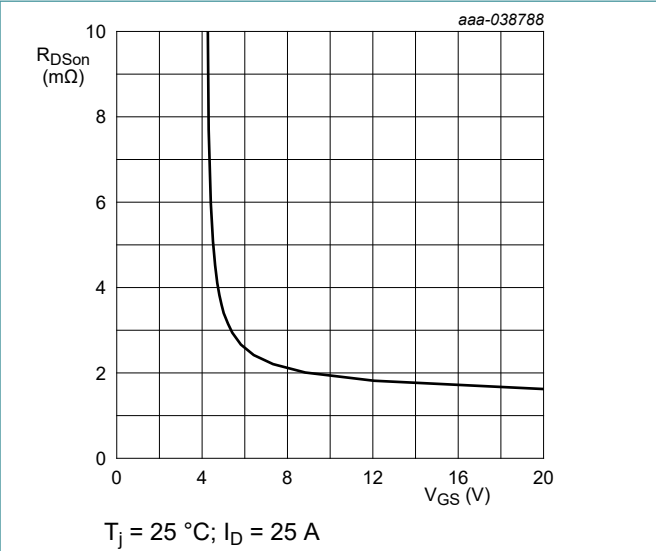
**Table 7. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise stated.

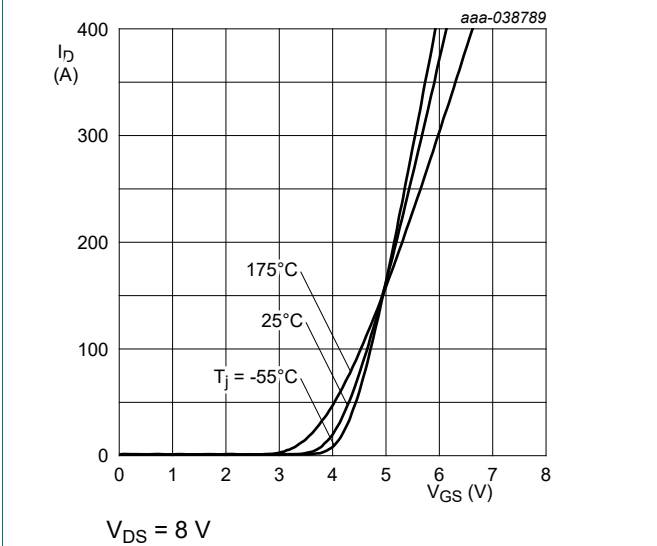
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}; V_{GS} = 0\ \text{V}; T_j = 25\text{ °C}$	80	87	-	V
		$I_D = 250\ \mu\text{A}; V_{GS} = 0\ \text{V}; T_j = -40\text{ °C}$	-	85	-	V
		$I_D = 250\ \mu\text{A}; V_{GS} = 0\ \text{V}; T_j = -55\text{ °C}$	72	84	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ \text{mA}; V_{DS}=V_{GS}; T_j = 25\text{ °C};$ <a href="#">Fig. 9</a>	2	3	4	V
		$I_D = 1\ \text{mA}; V_{DS}=V_{GS}; T_j = 175\text{ °C};$ <a href="#">Fig. 10</a>	1	1.9	-	V
		$I_D = 1\ \text{mA}; V_{DS}=V_{GS}; T_j = -55\text{ °C};$ <a href="#">Fig. 10</a>	-	3.3	4.6	V
$I_{DSS}$	drain leakage current	$V_{DS} = 80\ \text{V}; V_{GS} = 0\ \text{V}; T_j = 25\text{ °C}$	-	0.003	1	$\mu\text{A}$
		$V_{DS} = 80\ \text{V}; V_{GS} = 0\ \text{V}; T_j = 125\text{ °C}$	-	3	100	$\mu\text{A}$
		$V_{DS} = 80\ \text{V}; V_{GS} = 0\ \text{V}; T_j = 175\text{ °C}$	-	76	500	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 20\ \text{V}; V_{DS} = 0\ \text{V}; T_j = 25\text{ °C}$	-	2	100	nA
		$V_{GS} = -20\ \text{V}; V_{DS} = 0\ \text{V}; T_j = 25\text{ °C}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}; I_D = 25\ \text{A}; T_j = 25\text{ °C};$ <a href="#">Fig. 11</a>	1.3	1.9	2.4	m $\Omega$
		$V_{GS} = 10\ \text{V}; I_D = 25\ \text{A}; T_j = 105\text{ °C};$ <a href="#">Fig. 12</a>	2.2	3.1	4.3	m $\Omega$
		$V_{GS} = 10\ \text{V}; I_D = 25\ \text{A}; T_j = 125\text{ °C};$ <a href="#">Fig. 12</a>	2.5	3.4	4.9	m $\Omega$
		$V_{GS} = 10\ \text{V}; I_D = 25\ \text{A}; T_j = 175\text{ °C};$ <a href="#">Fig. 12</a>	2.8	4.4	5.5	m $\Omega$
$R_G$	gate resistance	$f = 1\ \text{MHz}; T_j = 25\text{ °C}$	0.4	0.8	1.6	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 25\ \text{A}; V_{DS} = 40\ \text{V}; V_{GS} = 10\ \text{V};$ <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>	42.5	85	127	nC
$Q_{GS}$	gate-source charge		8.8	22	35	nC
$Q_{GD}$	gate-drain charge		5.8	16.5	38	nC
$C_{iss}$	input capacitance	$V_{DS} = 40\ \text{V}; V_{GS} = 0\ \text{V}; f = 1\ \text{MHz};$ <a href="#">Fig. 15</a>	3510	5850	8191	pF
$C_{oss}$	output capacitance		554	1385	2493	pF
$C_{rss}$	reverse transfer capacitance		4	44	102	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 40\ \text{V}; R_L = 1.6\ \Omega; V_{GS} = 10\ \text{V};$ $R_{G(ext)} = 5\ \Omega$	-	19	-	ns
$t_r$	rise time		-	18	-	ns
$t_{d(off)}$	turn-off delay time		-	53	-	ns
$t_f$	fall time		-	29	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 25\ \text{A}; V_{GS} = 0\ \text{V}; T_j = 25\text{ °C};$ <a href="#">Fig. 16</a>	-	0.79	1	V
$t_{rr}$	reverse recovery time	$I_S = 25\ \text{A}; dI_S/dt = -100\ \text{A}/\mu\text{s}; V_{GS} = 0\ \text{V};$	-	38	-	ns
$Q_r$	recovered charge	$V_{DS} = 40\ \text{V};$ <a href="#">Fig. 17</a>	-	33	-	nC



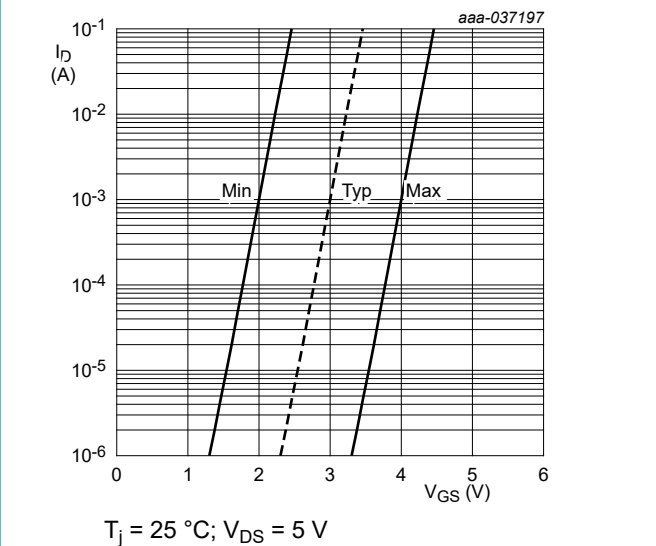
**Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values**



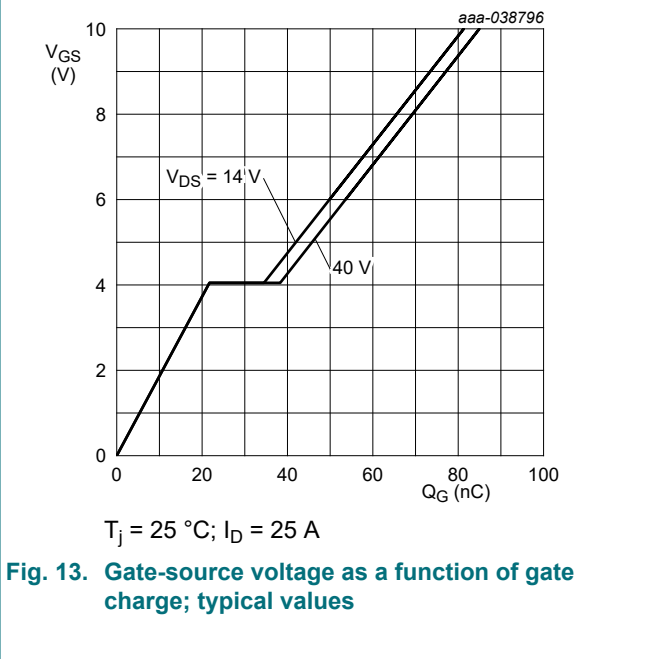
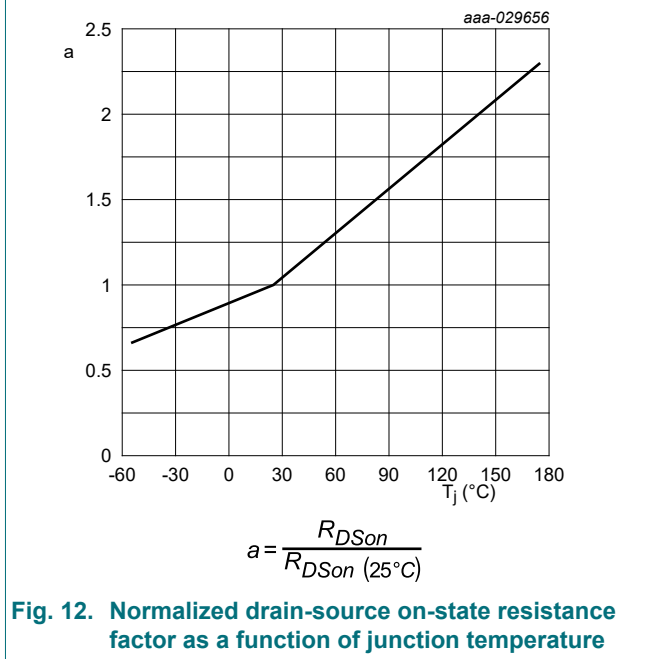
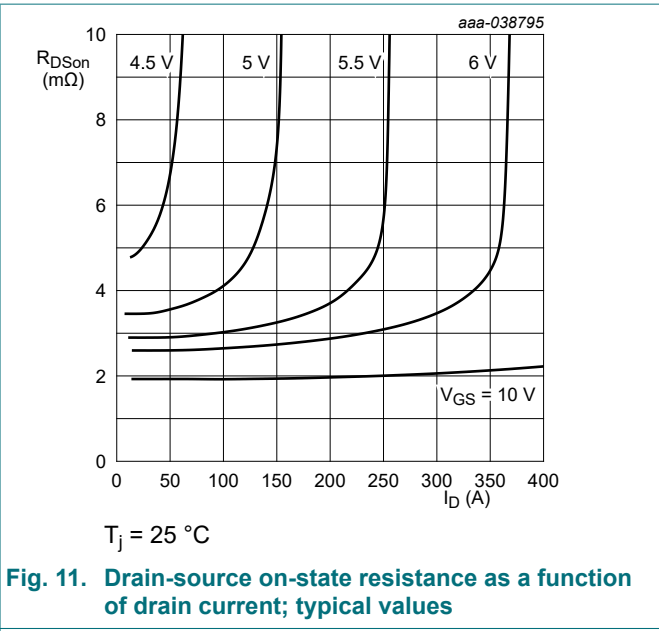
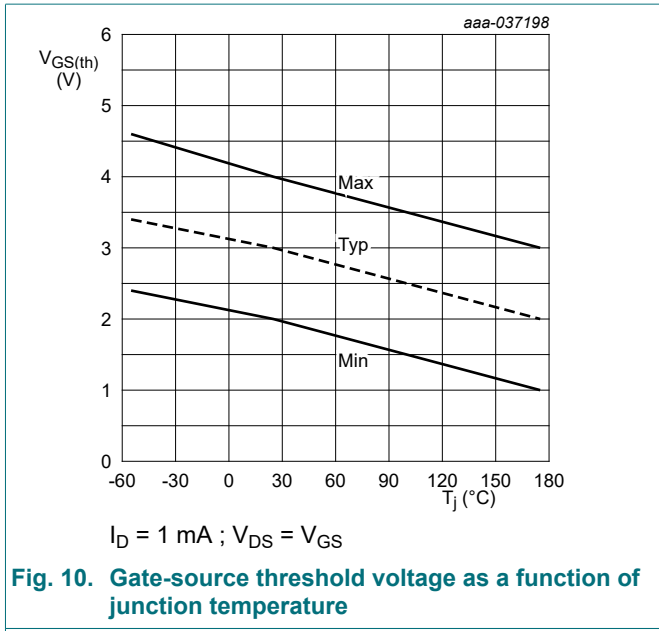
**Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values**



**Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values**



**Fig. 9. Sub-threshold drain current as a function of gate-source voltage**



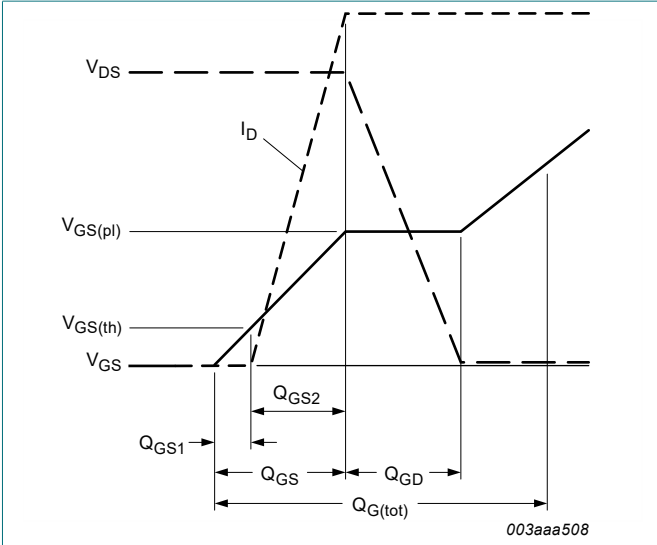


Fig. 14. Gate charge waveform definitions

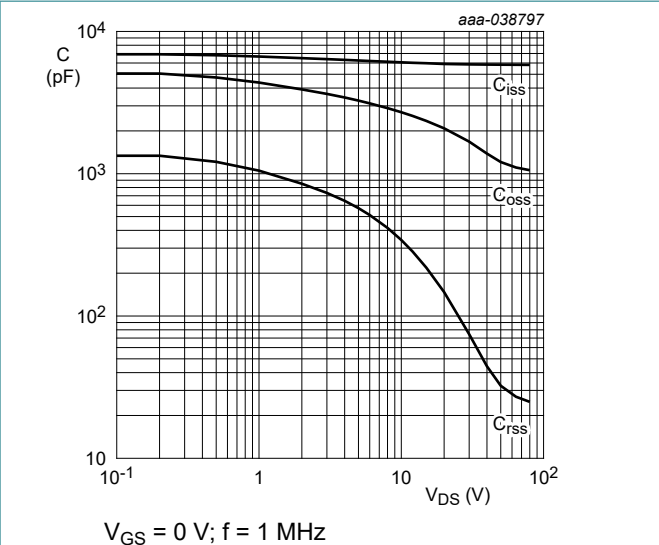


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

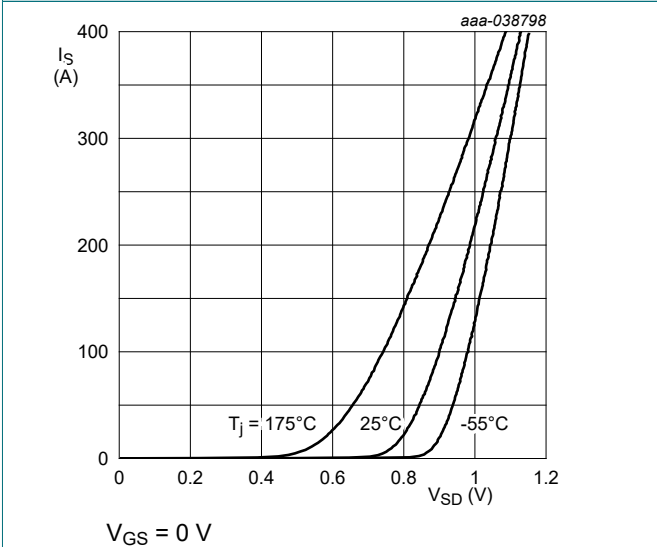


Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

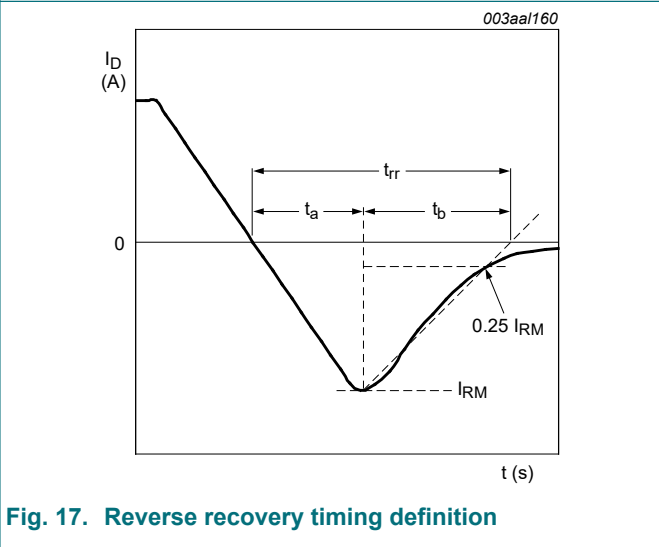
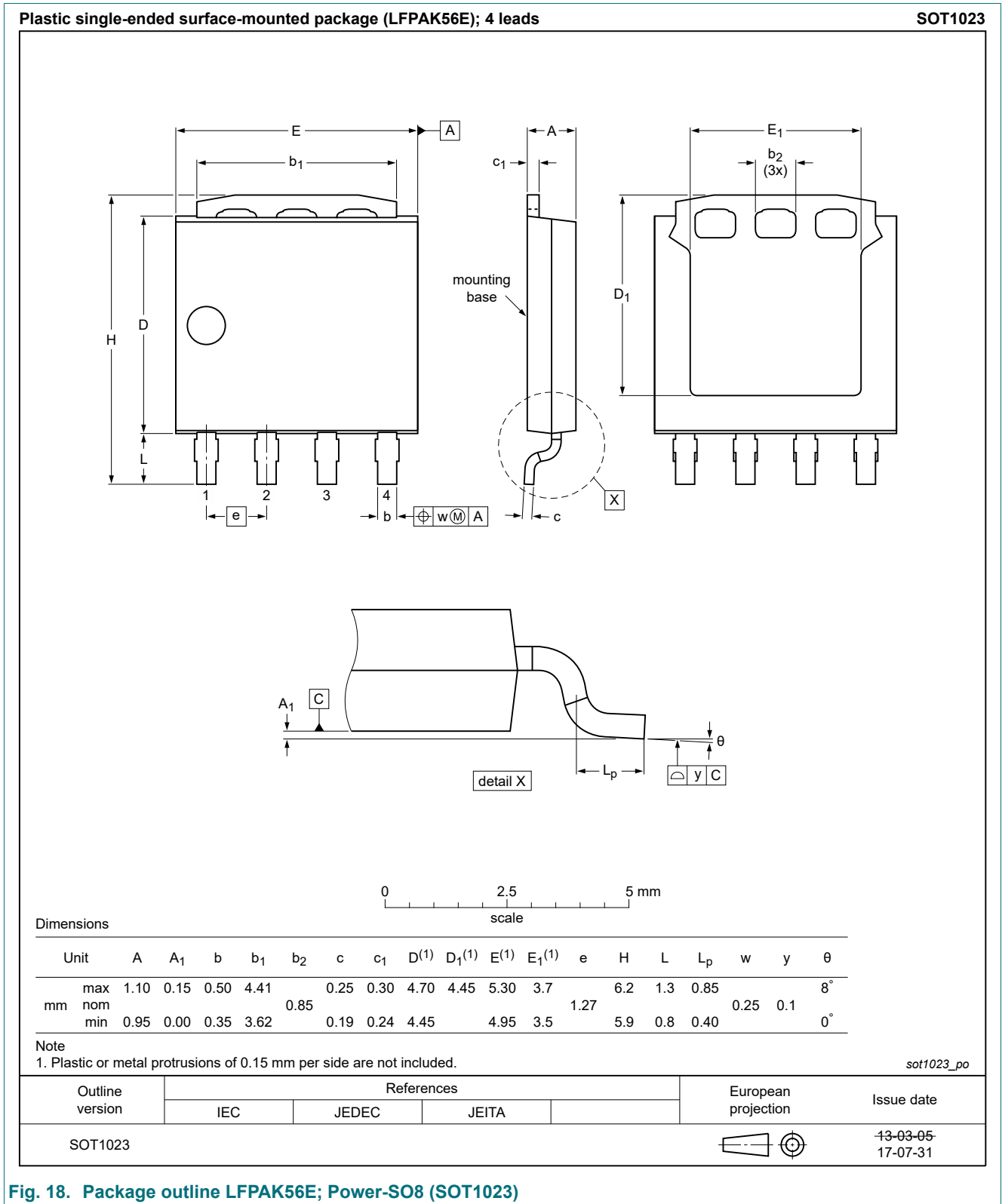


Fig. 17. Reverse recovery timing definition



### 11. Package outline



**Fig. 18. Package outline LPAK56E; Power-SO8 (SOT1023)**

## 12. Soldering

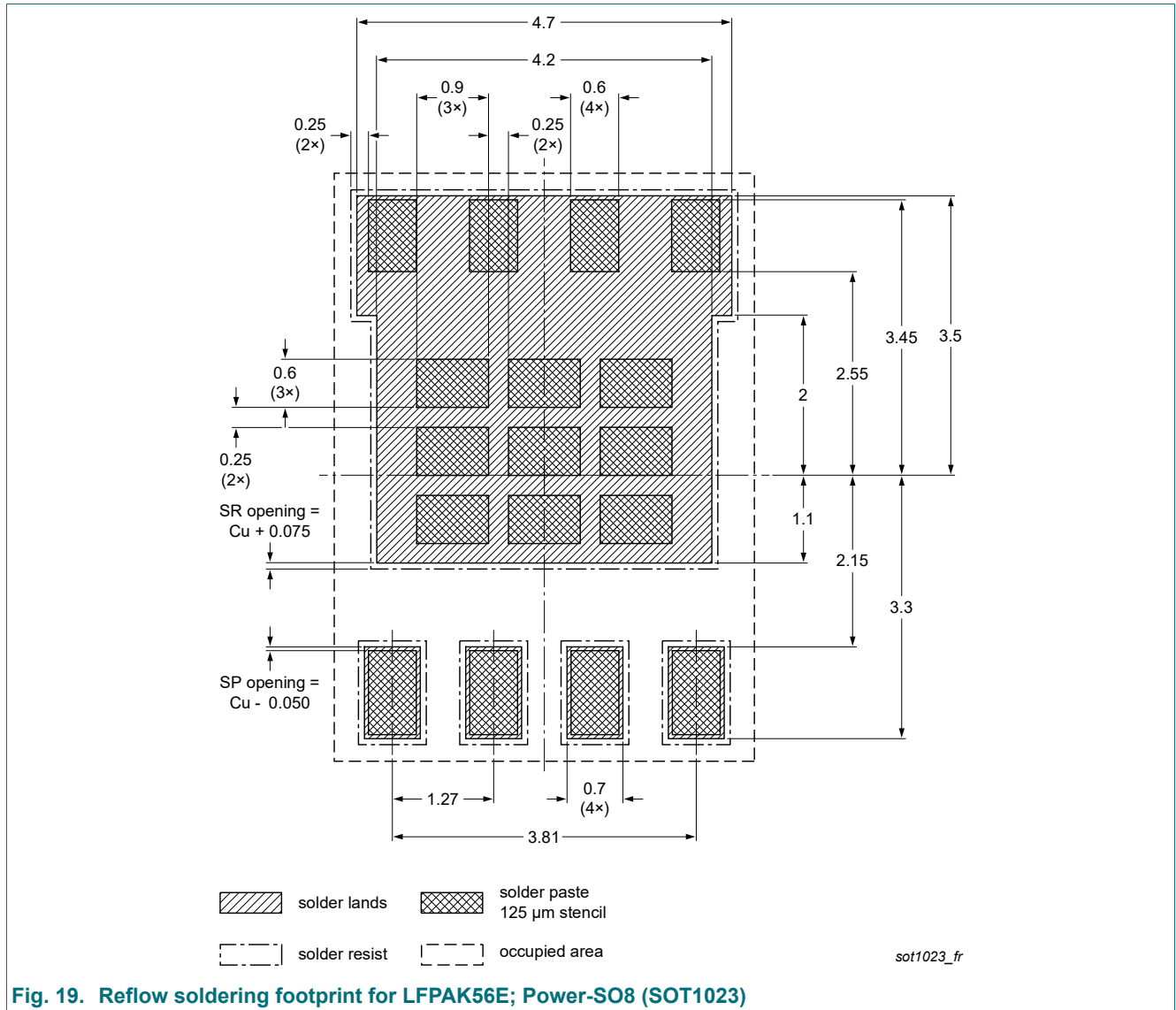


Fig. 19. Reflow soldering footprint for LPAK56E; Power-SO8 (SOT1023)

## 13. Legal information

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Document status [1][2]	Product status [3]	Definition
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